

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE PATENT
APPLICATION OF: **JEA GUN PARK, ET AL.**

SERIAL NO.: **10/540,992**

ATTORNEY DOCKET
NO.: **061063-0316598**

FILING DATE: **June 5, 2006**

CONFIRMATION NO.: **9014.**

ART UNIT: **1792**

EXAMINER: **ANGADI, Maki A.**

FOR: **CHEMICAL-MECHANICAL-POLISHING SLURRY COMPOSITION, METHOD FOR PLANARIZING SURFACE OF SEMICONDUCTOR DEVICE USING THE SAME, AND METHOD FOR CONTROLLING SELECTION RATIO OF SLURRY COMPOSITION**

RESPONSE TO NON-FINAL OFFICE ACTION

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Non-Final Office Action mailed August 13, 2008, the date for responding being extended by a one-month extension of time to December 13, 2008, please amend the above-identified application as follows:

Amendments to the claims begin on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.